3441/61

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

RICHARD M. WEBER ET AL.

Serial No. 08/406,226 (TI-19646)

Filed March 17, 1995

For: CONSTRUCTION OF PHASE CHANGE MATERIAL EMBEDDED ELECTRONIC CIRCUIT BOARDS AND ELECTRONIC CIRCUIT BOARDS ASSEMBLIES USING POROUS AND FIBROUS MEDIA

Art Unit 3407

Examiner C. Atkinson

Assistant Commissioner for Patents Washington, D. C. 20231

Sir:

AMENDMENT UNDER 37 C.F.R. 1.115

In response to the Office action dated November 22, 1995, please amend the above identified application as follows:

In the claims:

Amend claim 1 as follows:

1. (Amended) A heat sink which comprises:

(3)

- (a) an enclosure having a highly thermally conductive surface (5) region and defining an enclosed cavity;
- (b) a porous, highly thermally conductive material <u>integral</u> with and thermally coupled to said highly thermally conductive <u>surface and</u> disposed in said cavity [and thermally coupled to said thermally conductive surface]; and

3/1